RoHS	Compliance
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SPECIFICATIONS

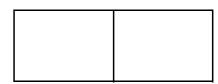
Messrs. Yangtech	Approved by

Product	CRYSTAL UNIT
Type of Holder	CM200C
Nominal Frequency	32.768 kHz
Customer's Parts Number	
Our Parts Number	

Sales CITIZEN FINETECH MIYOTA Co.,LTD. Crystal Devices Department.

Manufacturer 4107-5,MIYOTA,MIYOTA-MACHI,KITASAKU-GUN,NAGANO,389-0295,JAPAN

TEL : +81-267-32-2336 FAX : +81-267-32-3520



Revision History

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					Page : 2 OF 9			
Record		Page	Section	Changes	Prepared			
Revision number								
1 st	2010/06/21							
1								

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1. Scope

This document contains specifications for the crystal unit to be supplied by CITIZEN FINETECH MIYOTA Co.,LTD.

- 1.1 If something defined ambiguously or undefined in document happened, the customer and CITIZEN FINETECH MIYOTA would discuss and take necessary steps by mutual consent.
- 1.2 Product test data can't be attached to this document.

 The contents except Electrical Specifications in specifications are subject the change without notice.
- 1.3 This product is not authorized for use as a critical component in life support devices or systems.

2. Electrical Specifications

2.1 Nominal Frequency 32.768 kHz

2.2 Operating Temperature Range $-40 \sim +85$

2.3 Storage Temperature Range $-55 \sim +125$

2.4 Frequency Tolerance ±20ppm Max. at 25

2.5 Frequency Tolerance over Turnover Temp.; 25±5

Operating Temperature Range Temp.Coefficient: -0.034±0.006ppm / 2

2.6 Equivalent Series Resistance $50k\Omega$ Max.at 25

2.7 Insulation Resistance 500M Ω Min./DC100V \pm 15V

2.8 Shunt Capacitance 1.35pF Typ

3. Test Conditions

3.1 Load Capacitance 12.5 pF

This Load Capacitance has been fixed on customer's

request.

3.2 Level of Drive 1µW Max.

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4. Mechanical and Environmental Tests

Test Name Test Conditions		Test Conditions	Criteria		
1.Mechanical Tests					
1-1	Shock Drop 3 times from the height of 75 cm onto hard wooden board with thickness of 3 cm.				
1-2	Vibration	Vibration Frequency: 10 to 500 Hz, 1.5mm, full wave, or acceleration 10G,			
		Cycle: 1.5 minutes, Direction: X.Y.Z.	Α		
		Time: 2 hours in each direction, for 6 hours in total.			
1-3	Solderability	After applying RMA flux, dip in solder. Dipping Time: 5+/-0.5seconds.	С		
		Soldering Temperature : 230+/-5 degC.			
1-4	Reflow Soldering	See Fig.1 reflow condition.	В		
	Heat Resistance				
1-5	Sealing Tightness	Leak rate shall be measured by using Helium Leak Detector.	D		
2 . E	Environmental Te	sts			
2-1	Storage In	Expose the sample in an inoperative mode to 500 hours at -40 .	A		
	Low Temperature				
2-2	Storage In	Expose the sample in an inoperative mode to 500 hours at +85 .	В		
	High Temperature				
2-3	Humidity	Expose the sample in an inoperative mode to 500 hours at +65 , and 95%RH.	В		
2-4	Thermal Shock	Subject the sample to 5 temperature variation cycles at -40 for 30 minutes	A		
		and +100 for the next 30 minutes in each cycle.			

Criteria

Criteria	Criteria
A	Any variation between the pre- and post-test frequencies shall remain within ±5ppm.
	The equivalent series resistance shall remain within its specified tolerance range after the post-test.
В	Any variation between the pre- and post-test frequencies shall remain within ±10ppm.
	The equivalent series resistance shall remain within its specified tolerance range after the post-test.
C	At least 90% of each dipped area shall be covered by fresh solder.
D	$1\times10^{-2}\mu\text{Pa}\cdot\text{m}^3/\text{s Max}$.

Measurements should be taken place at 25+/-2 degC after each test, the samples shall be left at 25 degC for one to two hours.

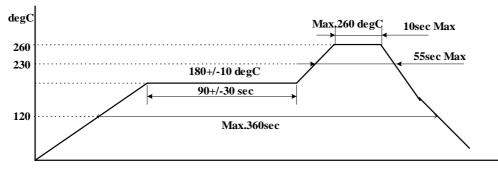
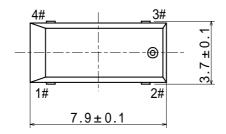


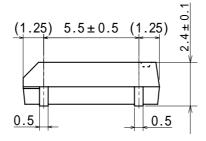
Fig.1

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5. Dimensions

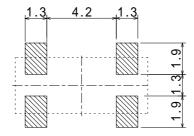
(unit:mm)



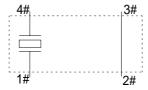




6. Solder Pad Layout



Intermal connection



Do not connect to external with #2 and #3.

Marking Standards

32Cyww

32C: Manufacture's ID Code

y: The last digit of production year. ww: Week Code

Table 1

Month	1	2	 9	10	11	12
Code	1	2	 9	X	Y	Z

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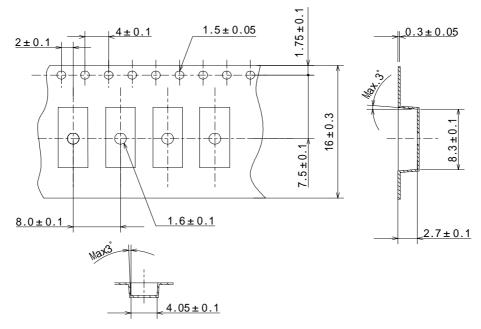
9. Tape and Reel Packaging

(unit:mm)

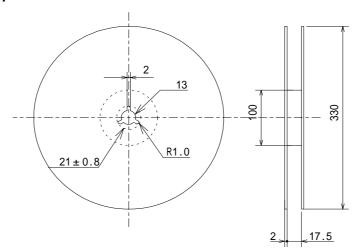
(1) Taping Specification

Conforming to JIS C 0806-3

[Tape Dimensions]

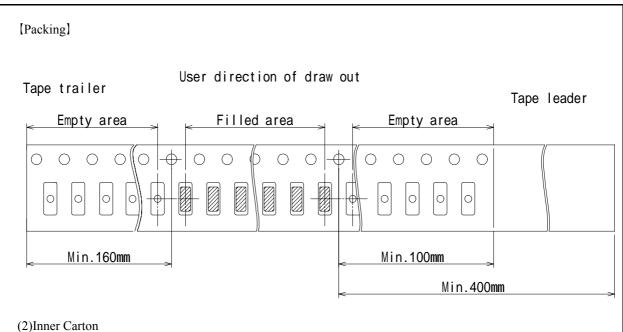


[Reel Dimensions)]



Material(Carried tape) : Clear PS Material (Cover tape) : Clear PS Material (Reel) : PS

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[Bar Code Label]

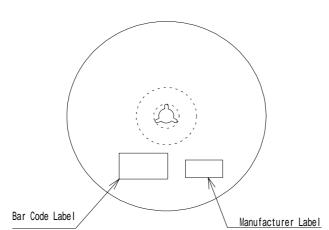
a	Customer P/N	CITIZEN	f
		CM200C	g
b	Quantity	Made in China	h
		RoHS Compliance	i
С	CITIZEN P/N		
•			
d	Ctl No. Spec		;
a			
	LotNo		
e			

- a. Customer P/N
- b. Quantity
- c. Our P/N
- d. Control No.
- e. Lot No.
- f. Manufacturer's name or symbol
- g. Type of Holder
- h. Country of Origin
- i. RoHS Compliance
- j. Spec.

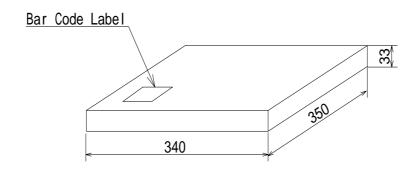
Nominal Frequency Load Capacitance Frequency Tolerance Equivalent Series Resistance Our character code

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[Reel]



[Inner Carton for 1 reel]



(3)Quantity

3000pcs/reel

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10. Manufacturer

MASTER CROWN ELECTRONICS (WUZHOU) LIMITED. No3 BUILDING 137.XINXING ER ROAD, WUZHOU, GUANGXI, CHINA

TEL: +86-774-3863148

Country of Origin : CHINA

* This manufacture is under the control of CITIZEN FINETECH MIYOTA CO.,LTD.

11. Ozone Depleting Substance (ODS)

This Product doesn't use the class ODS at any of production processes, and component parts.

12. Precautionary Statement

12-1 When dropped by mistake

The crystal products are designed and manufactured to resist physical shocks. However,in the event the crystal is subjected to excessive impact such as being dropped onto the floor or giving shocks during mounting. Need to make sure its satisfactory performance before using it.

Mounting of quartz crystal units onto circuit board

When using an automatic loading machine, test and confirm to cause on the crystal products before mounting.

Bending the circuit board in the process of cleaving boards after mounting and soldering crystal products may cause peeling off the soldering or package cracks by mechanical stress. Please be sure that the layout of crystal products position is on the less stressed and the cleaving process is under less stressed for crystal products.

12-3 Cleaning

- (1) Crystal products may be affected and destroyed at worst by ultrasonic cleaning. Please be sure to check if your cleaning process affects any damage to crystal products prior to use.
- (2) Some kind of cleaning fluid may cause any damage to crystal products . Please be sure to check suitability of the cleaning fluid in advance.

12-4 Storage

Storage of Crystal products under higher temperature or high humidity for a long term may affect frequency stability or solderability. Please store the Crystal products under the normal temperature and humidity without exposing to direct sunlight and dew condensation, and avoid the storage of Crystal products for more than 6 months, and mount them as soon as possible after unpacking.

13. QC Process Chart

Refer to attached sheet

QC工程図	水晶振動子 CM200C/CM25	0C		2009年4月28日		承認	審査 担当
Q C Process Chart Quartz Crystal Unit			April 28 2008 水晶デバイス部 技行		課	Approved	Checked Prepared
			Crystal De	vices Div. Production of the p	tion Dept. ction	想	
工程	型		工程名	Cont	管理仕様 rol Specifications	8	記録
Flow	chart	_	Process Name	管理項目 Control Item	管理規格 Control Criteria		Record
水晶片 Crystal Element	START	1	受入検査 (水晶片) Acceptance Inspection (Crystal Element)	仕様 Specification	納入仕様書 Specifications	品質受入 検査基準書 Quality Acceptance Inspection Standard	検査表 (水晶片) Inspection Sheets (Crystal Element)
気密端子 Heametically Sealed Base	2	2	蒸着 Evaporation	湿度 Humidity 真空度 Pressure トータル膜厚 Total Thickness	作業指示書 Manufacturing Process Instruction	-	記録紙 Printed Data 稼動表 Operating Sheets 推移グラフ Change Graph
4	3	3	周波数粗調整 Frequency Rough Tuning	周波数 Frequency 外観 Appearance	作業指示書 Manufacturing Process Instruction	抜取 Sampling 抜取 Sampling	チェックシート Check Sheets 送品検査表 Process Inspection Sheets
	5		受入検査 (気密端子) Acceptance Inspection (Heametically Sealed Base)	仕様 Specification	納入仕様書 Specifications	Quality Acceptance Inspection Standard	検査表 Inspection Sheets
封止管 Cap	6		Assembly	外観 Appearance	作業指示書 Manufacturing Process Instruction	全数 100%	チェックシート Check sheets
8	7		周波数微調整 Fine Tuning	周波数 Frequency	作業指示書 Manufacturing Process Instruction	抜取 Sampling	分布図 Distribution Chart
	9	7	アニール (半完成品) Annealing	真空度 Pressure 温度 Temperature 時間	作業指示書 Manufacturing Process	-	チェックシート Check Sheets チェックシート Check Sheets チェックシート
	10	8	受入検査 (封止管) Acceptance Inspection (Cap)	Time 仕様 Specification	納入仕様書 Specifications	品質受入 検査基準書 Quality Acceptance Inspection Standard	Check Sheets 検査表 Inspection Sheets
		9	封止 Sealing	真空度 Pressure 寸法 Dimension	作業指示書 Manufacturing Process	- 抜取 Sampling	チェックシート Check Sheets Xbar-R管理図 Xbar-R Control Chart
	13	10	ベーキング Baking	温度 Temperature 時間 Time	作業指示書 Manufacturing Process Instruction	-	チェックシート Check Sheets 作業履歴票 Manufacturing Record
	14		電気特性検査1 Electrical Characteristics Inspection 1 樹脂成型	電気的特性 Electrical Characteristics	作業指示書 Manufacturing Process Instruction	全数 100%	チェックシート Check Sheets チェックシート
	15	12	倒相及至 Molding	外観 Appearance	作業指示書 Manufacturing Process Instruction	全数 100%	Check Sheets
	16		印刷 Marking	印刷外観 Marking Appearance	印刷外観 Marking Appearance	全数 100%	チェックシート Check Sheets
	17	14	電気特性検査2 Electrical Characteristics Inspection 2	電気的特性 Electrical Characteristics	作業指示書 Manufacturing Process Instruction	全数 1	チェックシート Check Sheets
	END		テーピング Taping	テープ剥離強度 Strength of Peeling-Tapes	作業指示書 Manufacturing Process Instruction	抜取 Sampling	強度推移グラフ Strength -Transition Graph
			出荷判定 Delivery Judgment	電気的特性 Electrical Characteristics	Delivery Judgment Standard	抜取 Sampling	出荷判定成績表 Delivery Judgment Sheets
		17	梱包 Packing	個数 Quantity	梱包仕様書 Packing Specification	-	-